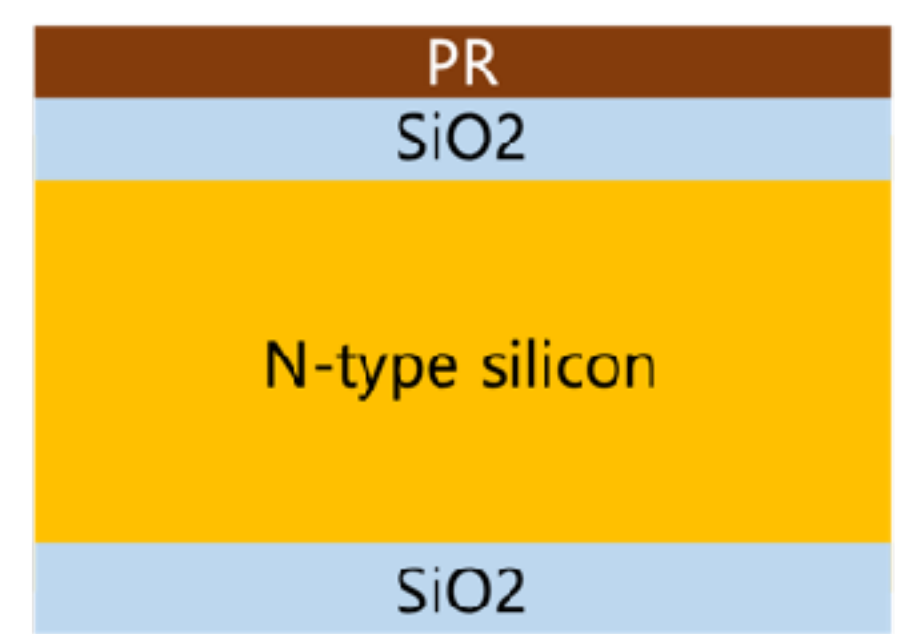
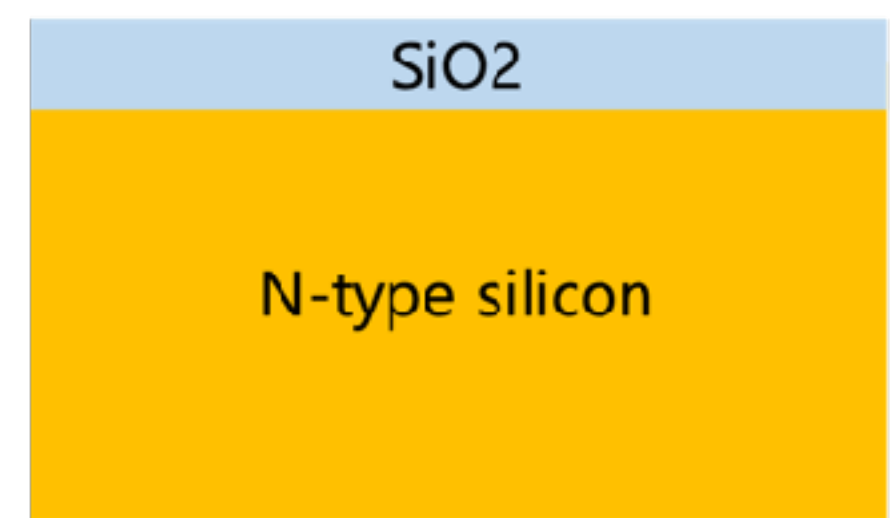


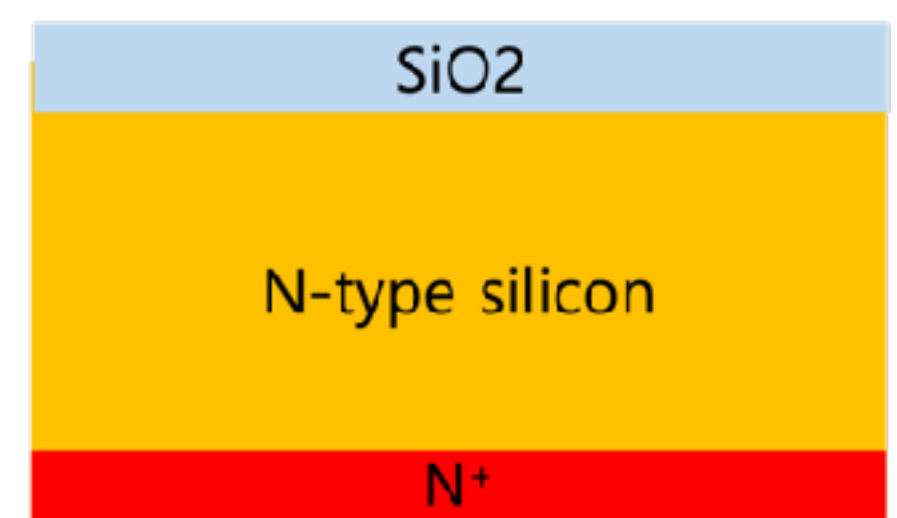
1. Oxidation [900°C, 6000Å]



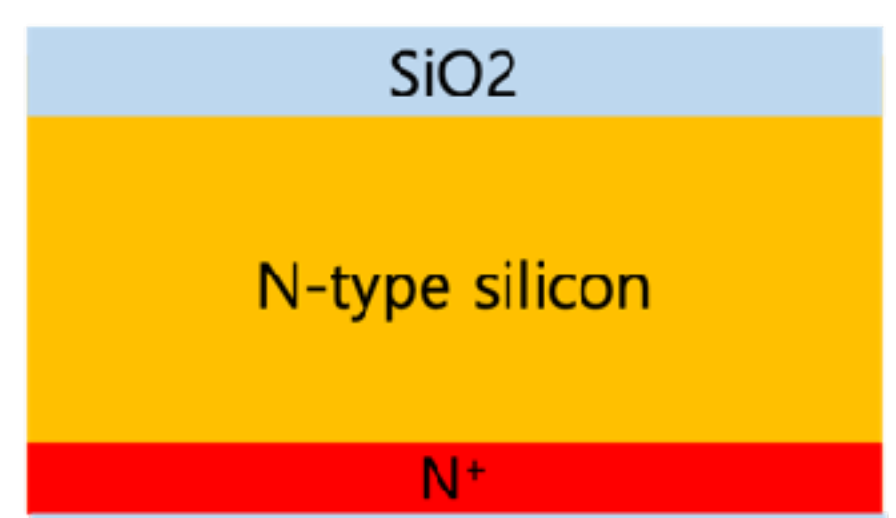
2. PR coating



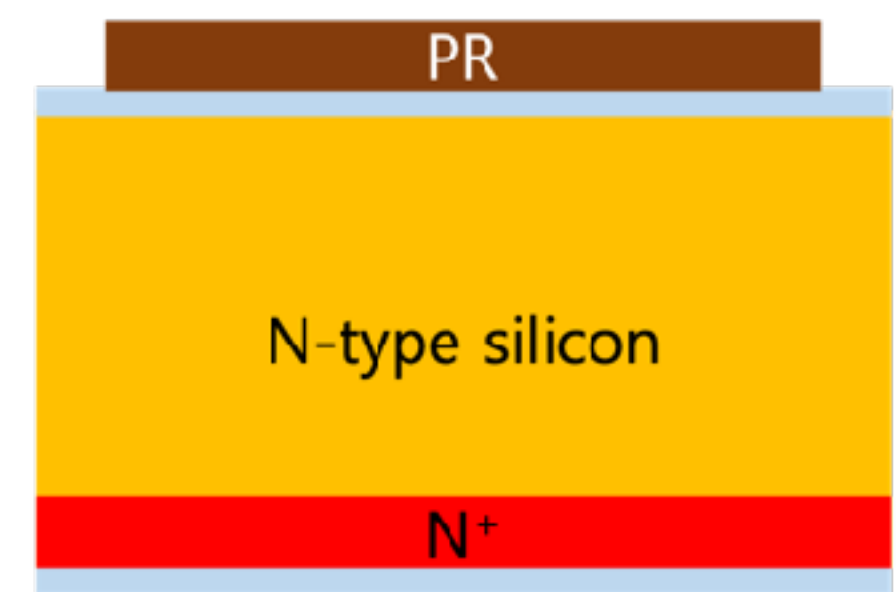
3. Backside Oxide strip
PR strip



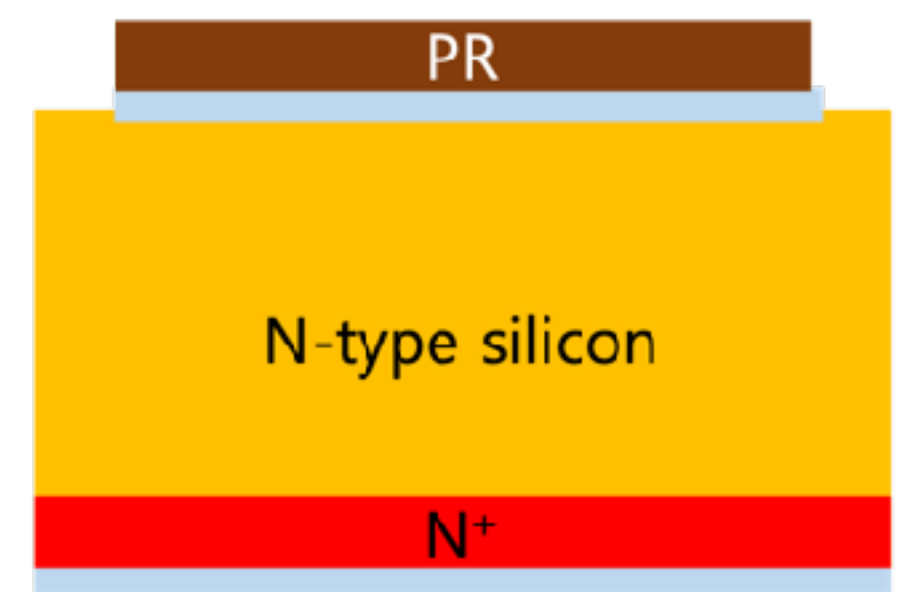
4. POCl3 Doping
Deglase PSG



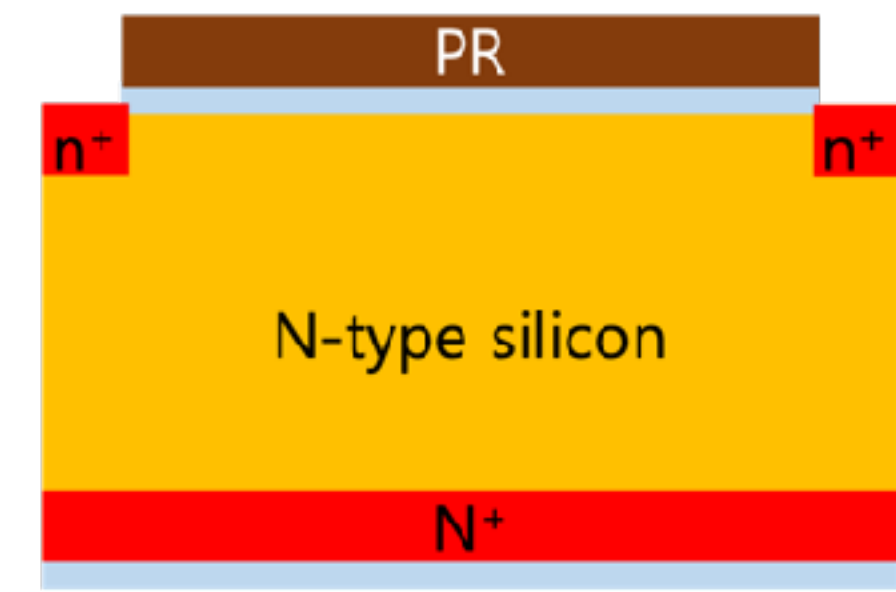
5. Oxidation [900°C, 1000Å]



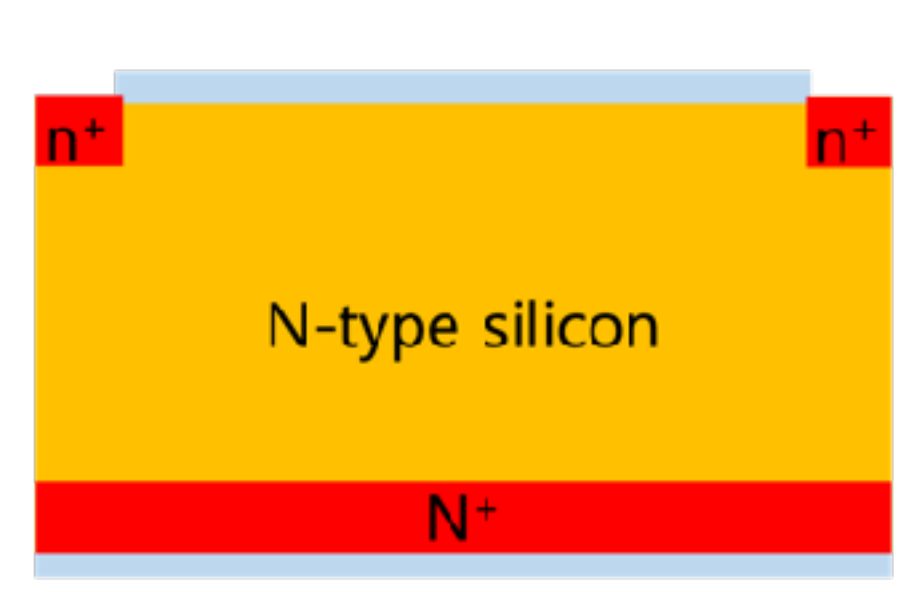
6. #Channel Stop Patterning



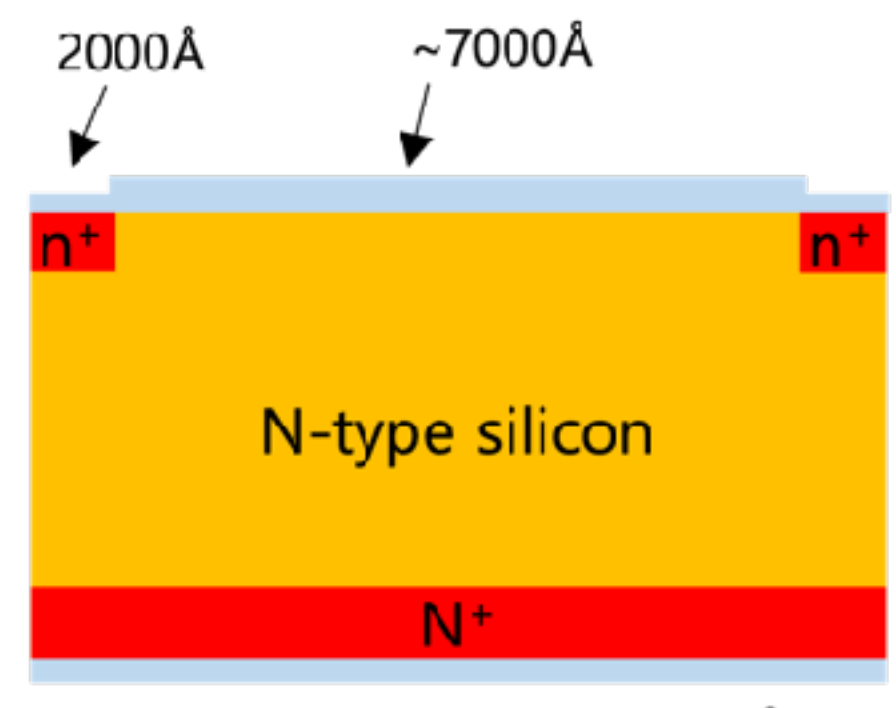
7. Oxide etch ~6000Å



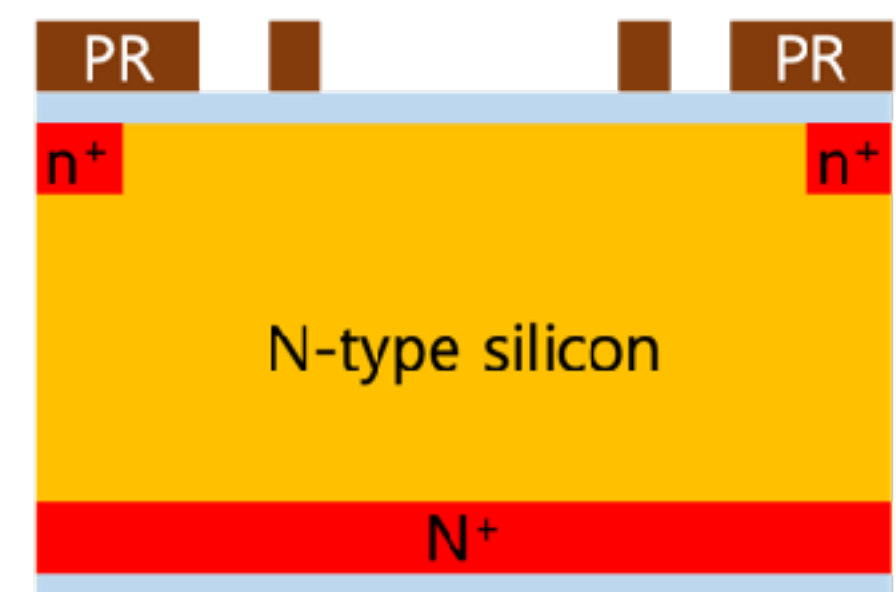
8. N+ implant [channel stop]
P31, 50KeV, 4.0E14/cm2



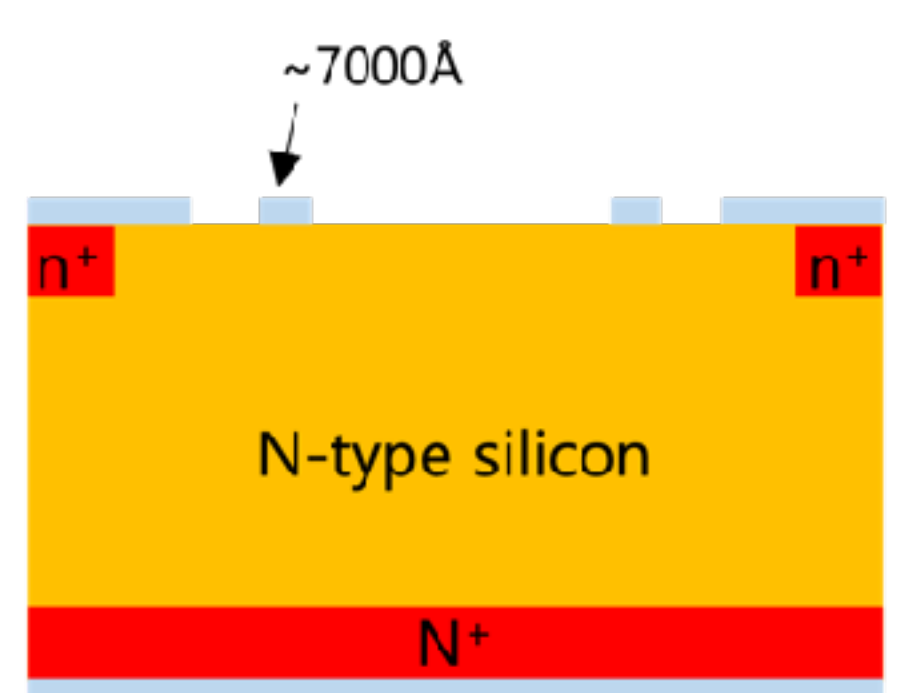
9. PR strip



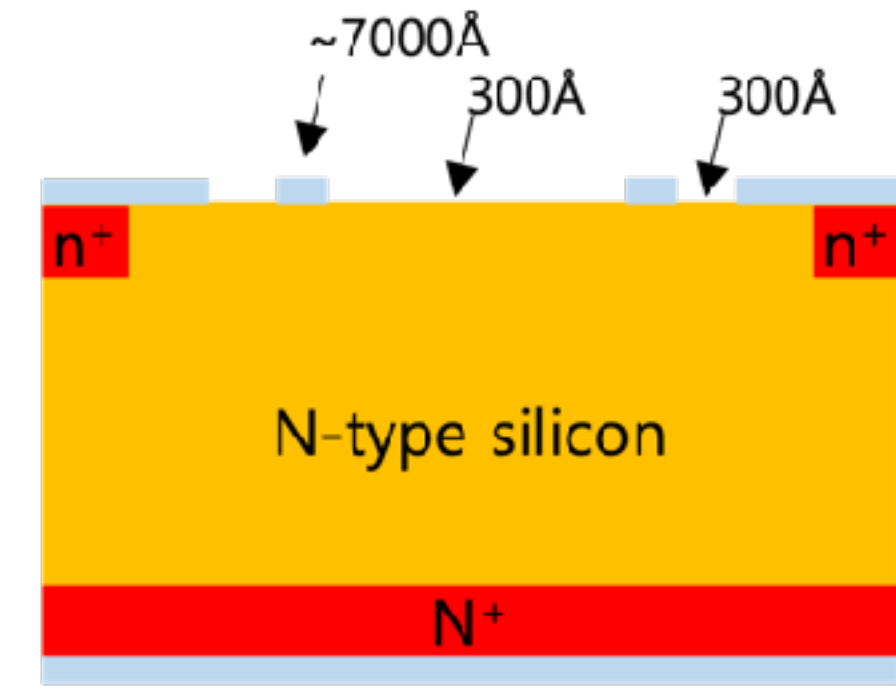
10. Oxidation [900°C, 2000Å]



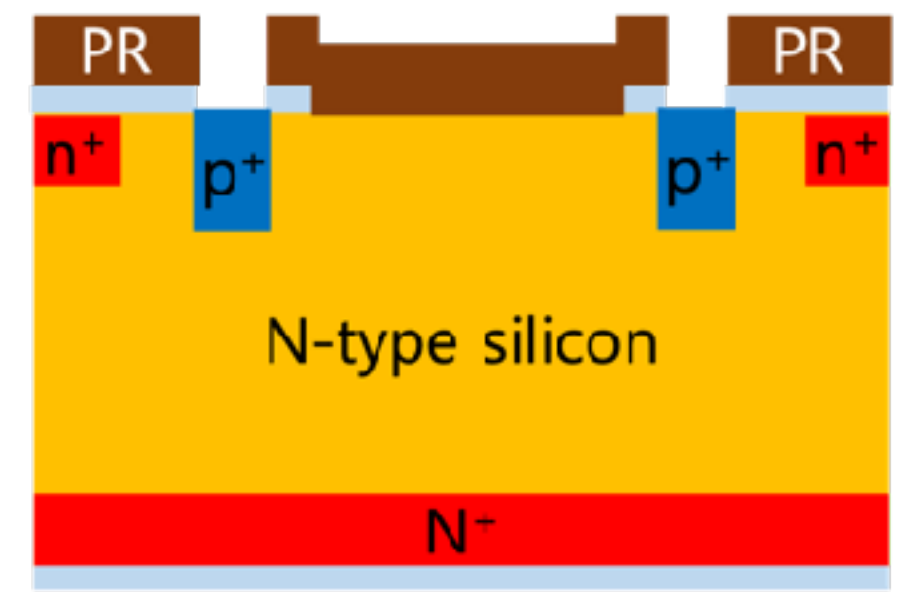
11. #Active Patterning



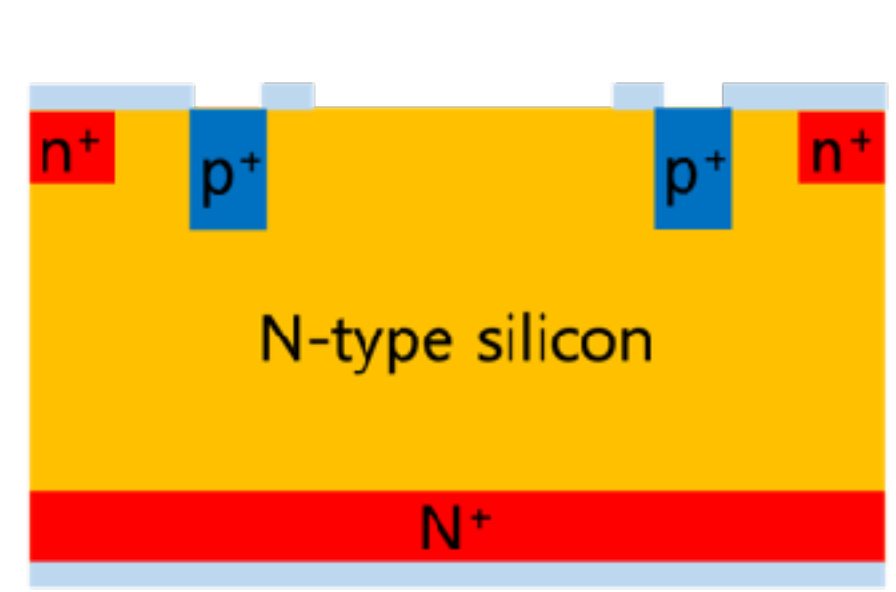
12-1. Oxide etch (Dry + Wet)
12-2. PR strip



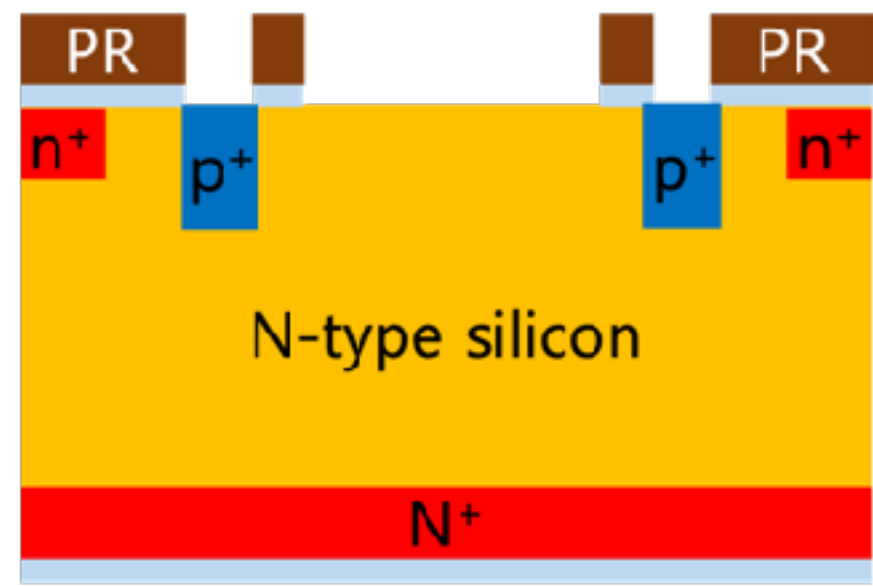
13. Oxidation [850°C, 300Å]



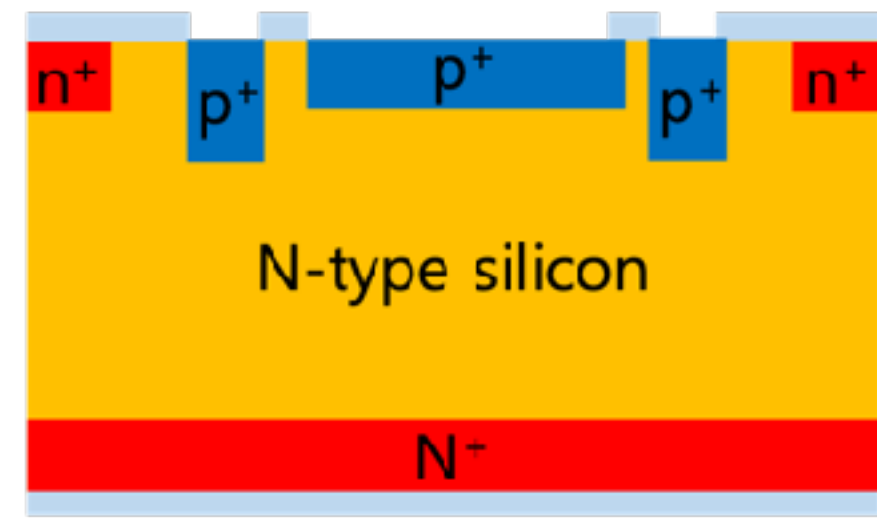
14-1. #GRD Patterning
14-2. P+ implant [GRD]
B11, 180KeV, 1.0E14/cm2



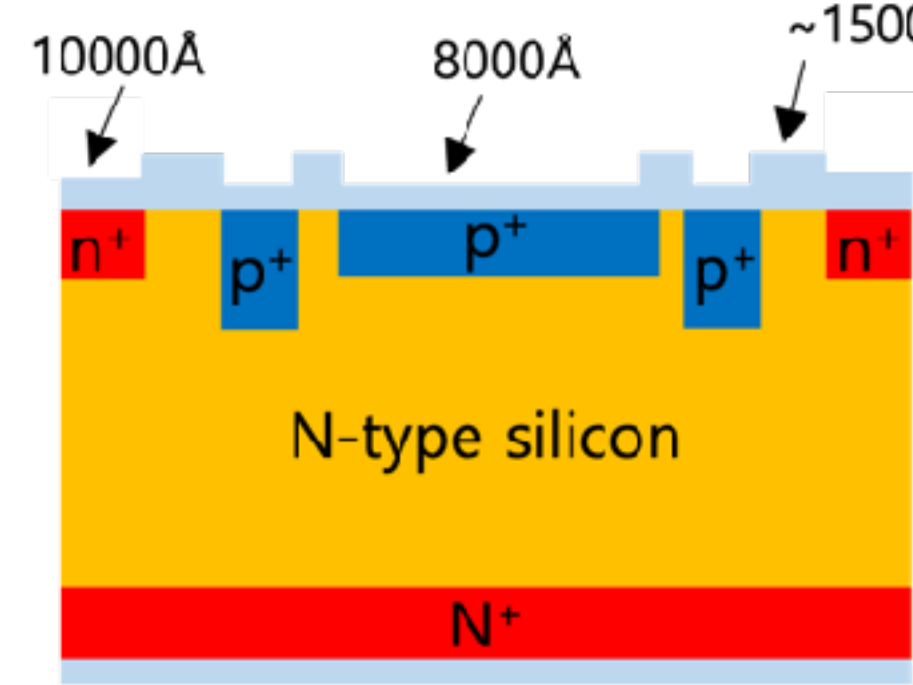
15-1. PR strip
15-2. Anneal (950°C, 60min)



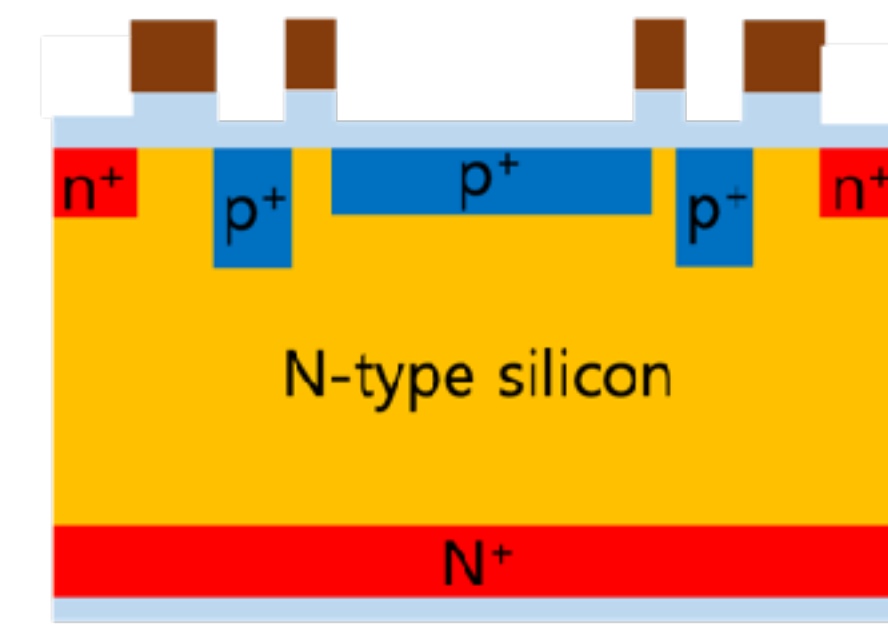
16-1. Active Patterning
 16-2. P⁺ implant [Active]
 B11, 50KeV, 1.0E15/cm²



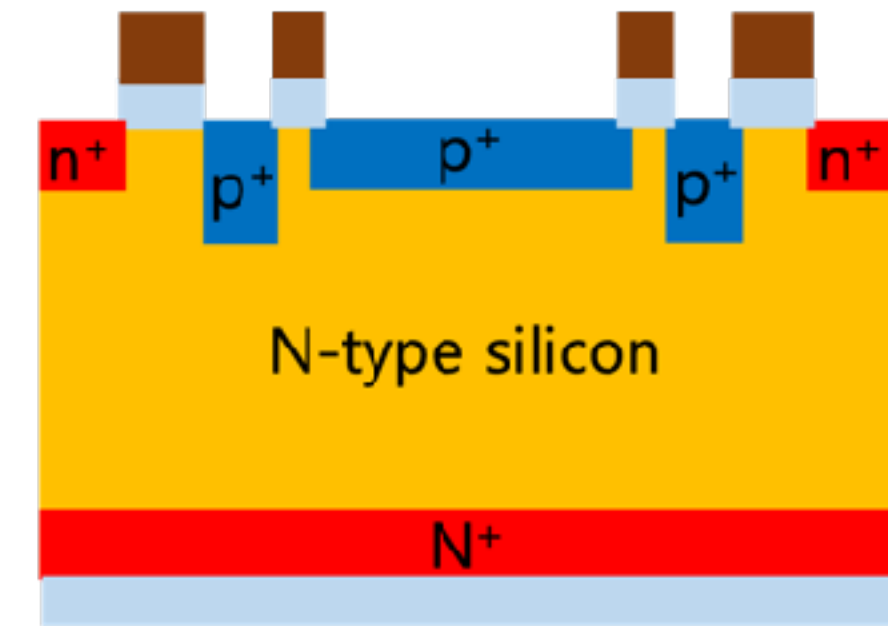
17. PR strip



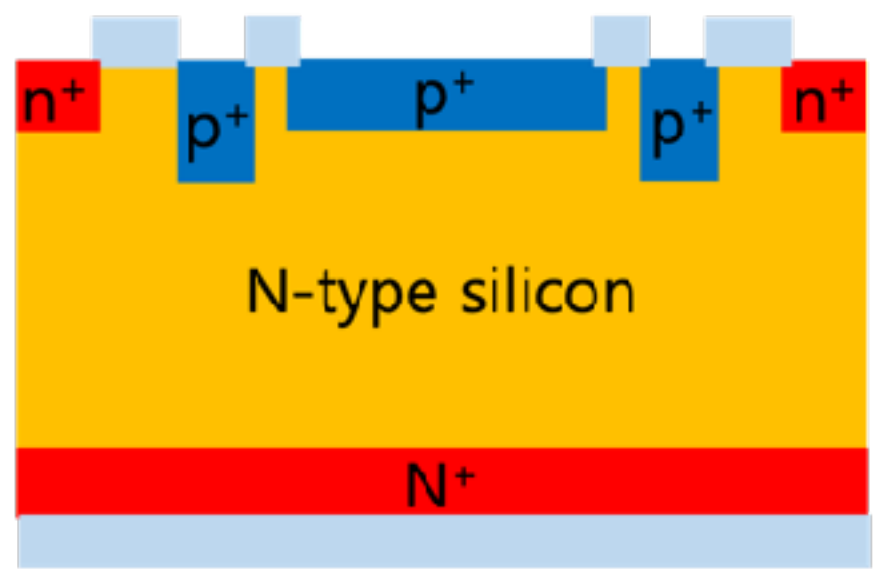
18-1. TEOS 8,000Å
 18-2. Anneal (950°C, 30min)



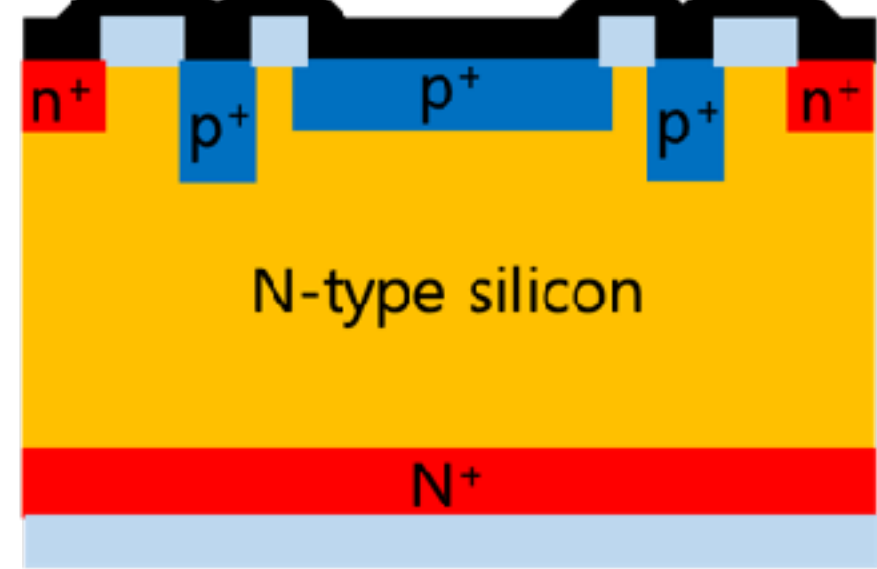
19. #CONT Patterning



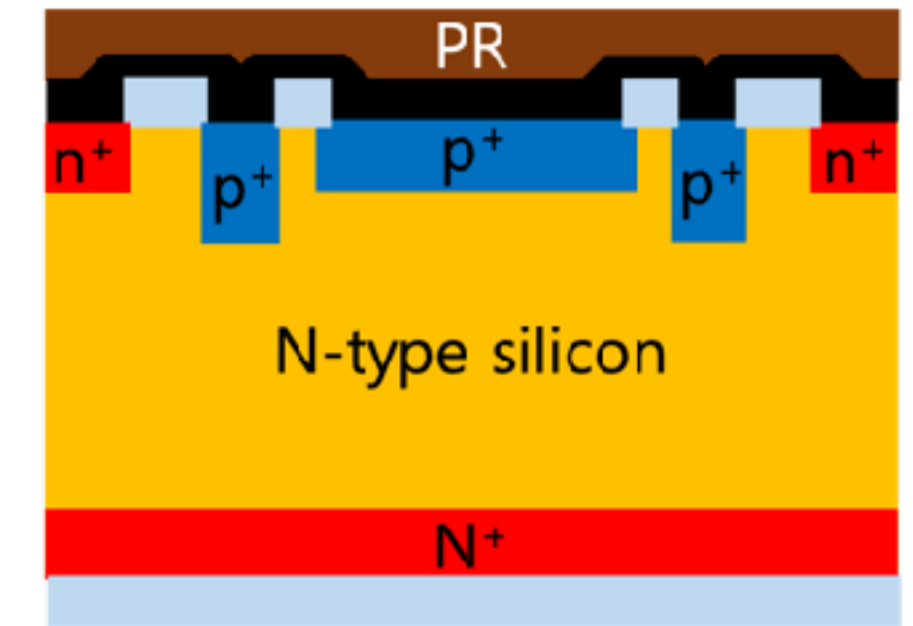
20. Oxide etch (Dry+Wet)
 Target: ~10000Å (oxide on n⁺)



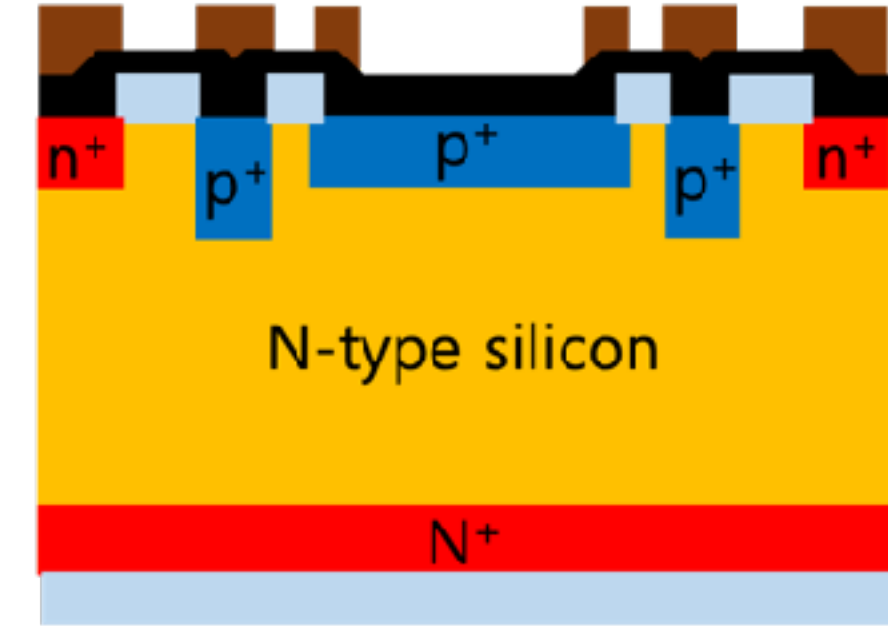
21. PR strip



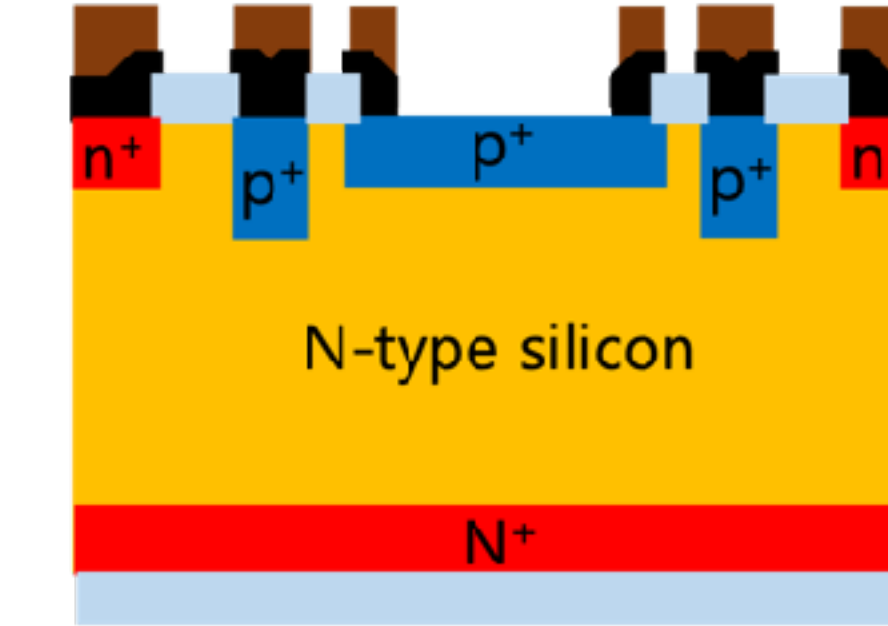
22. metal deposit
 [10000Å]



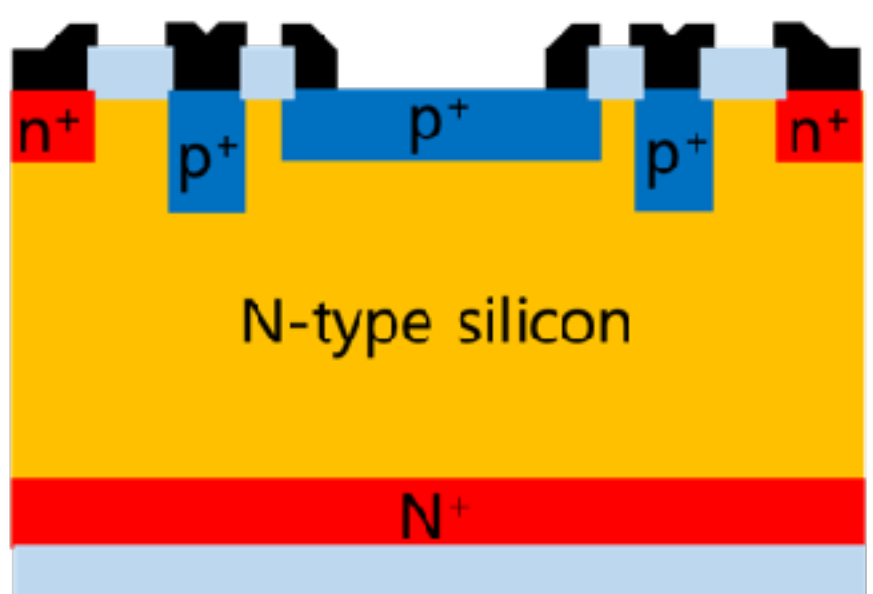
23. PR coating



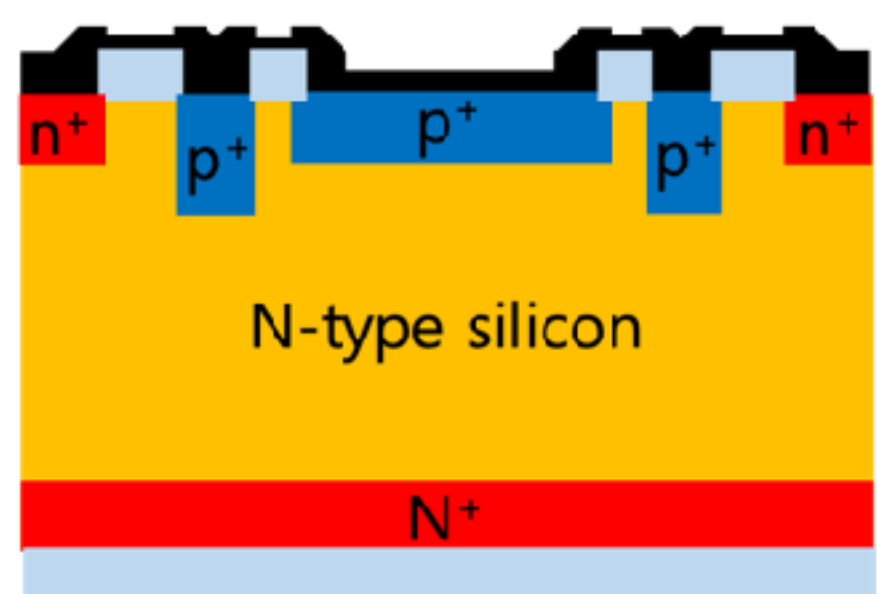
24. #GRD metal Patterning



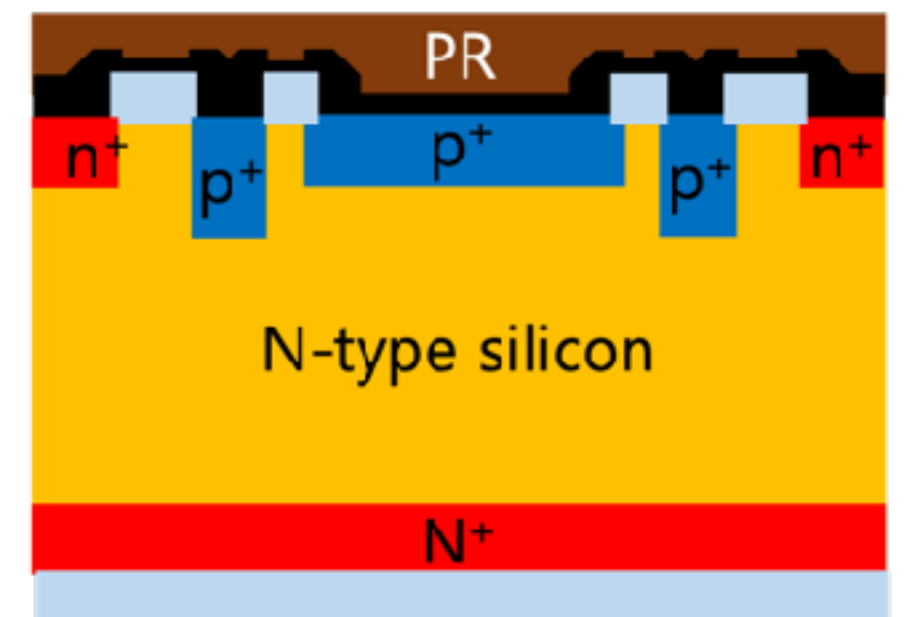
25. metal etching



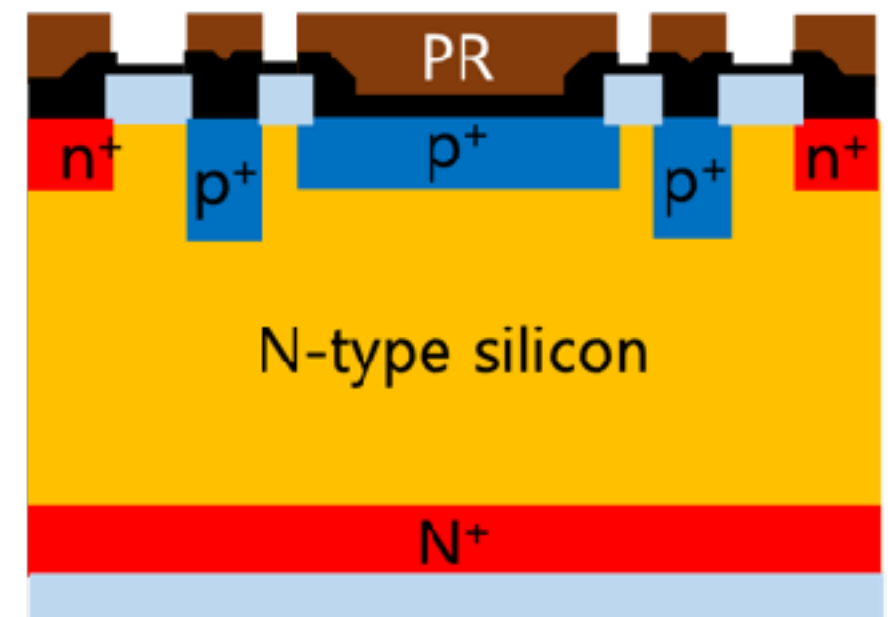
26. PR strip



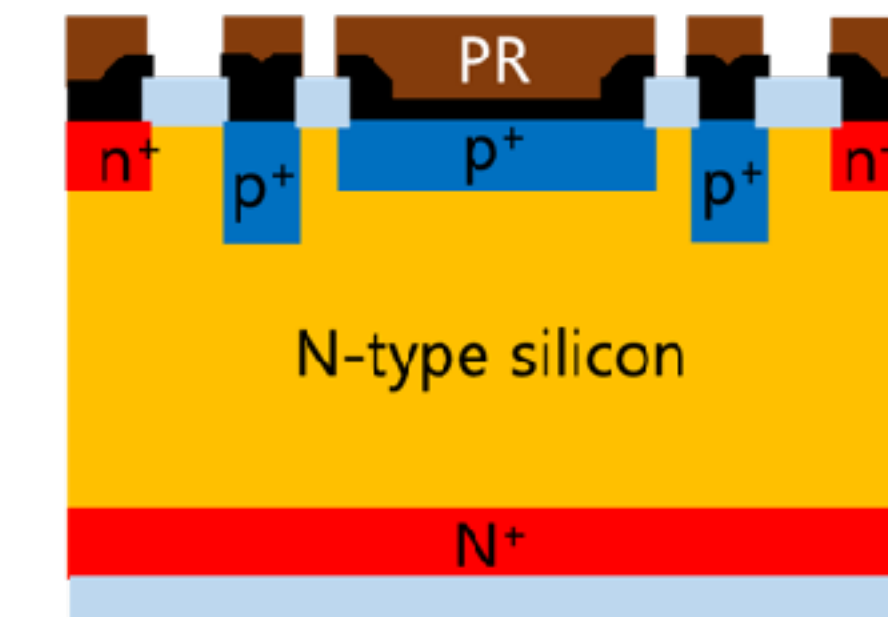
27. metal deposit
 [400Å]



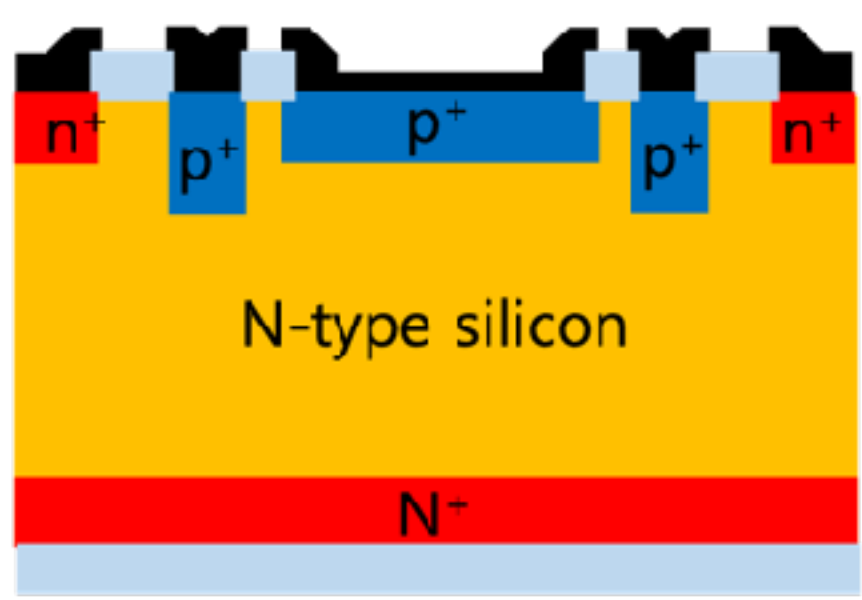
28. PR coating



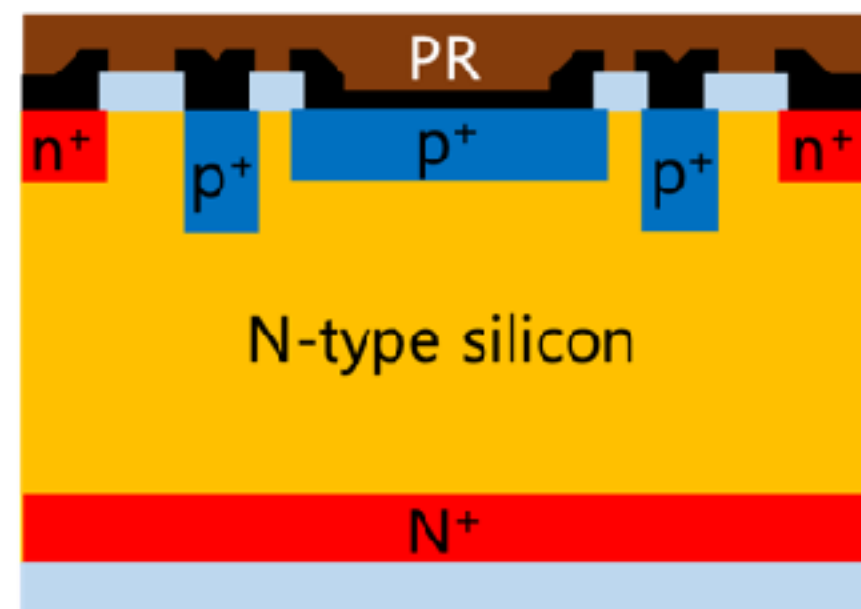
29. #ACT metal Patterning



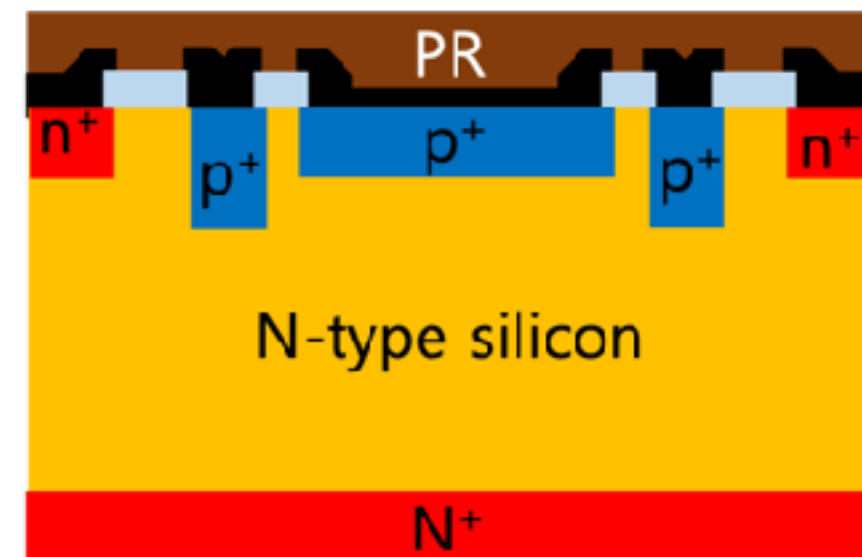
30. metal etching



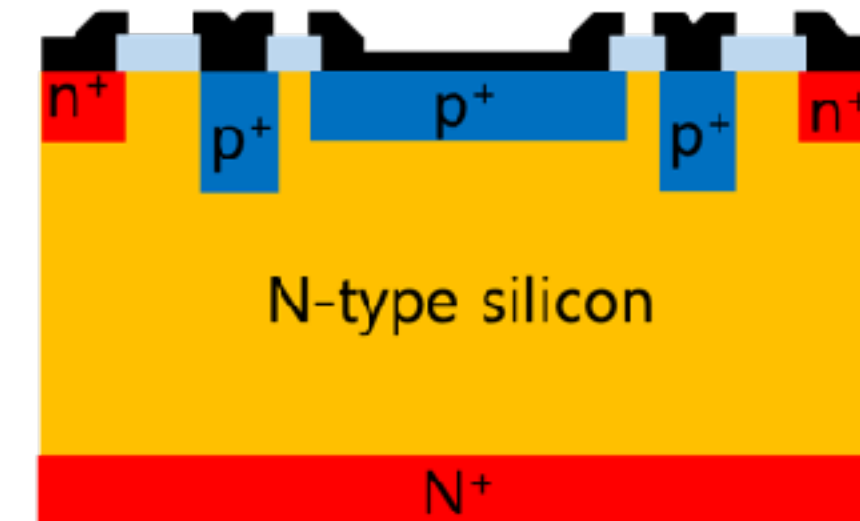
31. PR strip



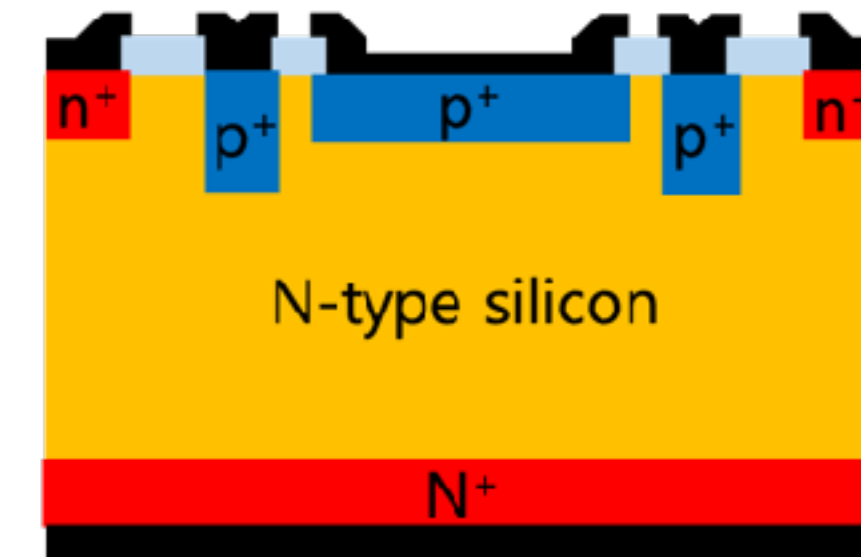
32. PR coating



33. oxide etching



34. PR strip



35-1. metal deposit [10000Å]
35-2. Alloy (420°C, 30min)



21. PR strip



22. metal deposit [10000Å]



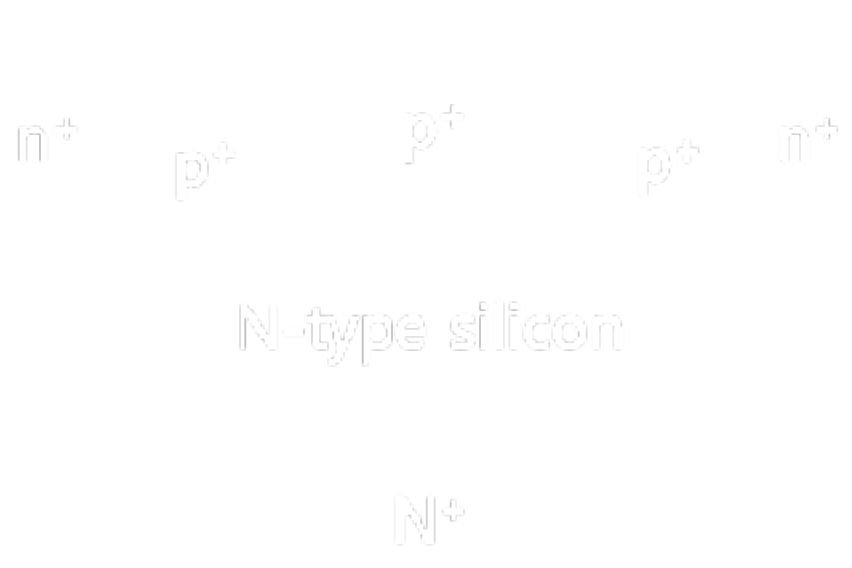
23. PR coating



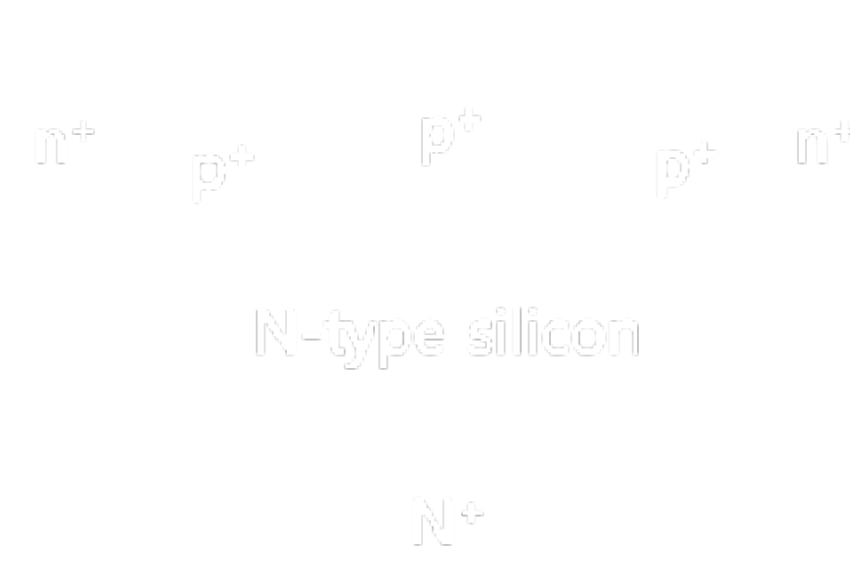
24. #GRD metal Patterning



25. metal etching



26. PR strip



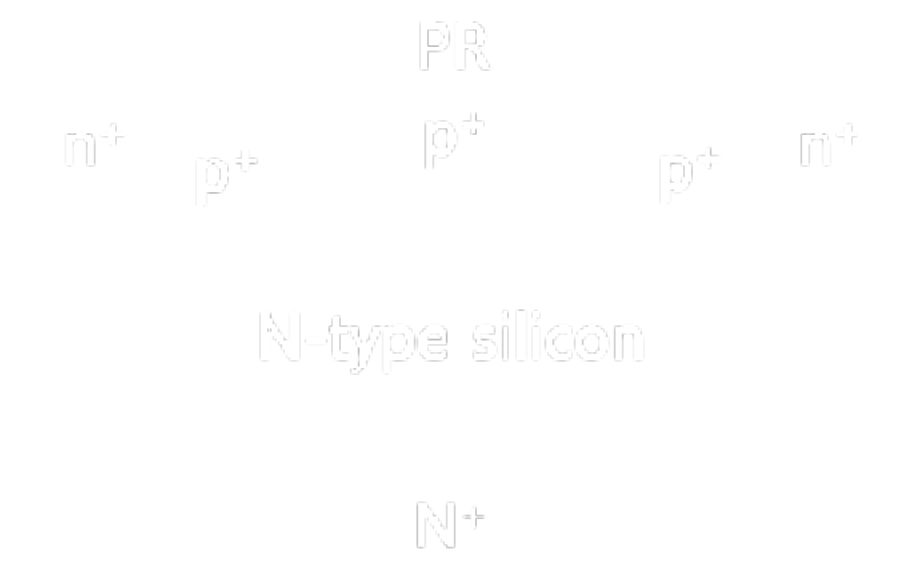
27. metal deposit [400Å]



28. PR coating



29. #ACT metal Patterning



30. metal etching